IPC ASSOCIATION OF ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.		der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					als and Mfg	Informati	ion	
upplier l	Information								,					
Company name* Company to				any unique ID			Unique ID Authority				Response Date*			
nsemi											2024-05-17			
Contact Nai	me	Title - Contact			F	Phone - Contact*				Email - Contact*				
Product-En	nv-Stewards		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
uthorized	Representative*	Title - Representative			F	Phone - Representative*			Email - Representative*					
Product-En	nv-Stewards	Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com				
]	Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	N	Manufacturing Site	We	eight*	UOM	Unit Type
	MC100EP195MNG BBG ECL PROG		BBG ECL PROG D	DELAY CHIP		2024-05-17 PH1		'H1	74.	3	mg	Each		
	turing Process Inform			All	CTD 020 MCI	D. C	D 1 D	D 1 T		M Ti , D l	T	N. 1	CD CL	,
2		,		STD-020 MSL	Rating	Peak Process Body Tempera		T *				per of Reflow Cyc	les	
•	Matte Tin (Sn) - annealed	[(CU Alloy	l			260		IC	30	seconds	3		
comments														
	ximum time at peak tempera													
or more in	formation regarding materia	al composition	please refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	led						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have not with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	ceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recurined by the						
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.67	mg	Supplier	Silicon (Si)	7440-21-3		1.67	mg
Die Attach	0.37	mg	Supplier	Isobornyl Methacrylate	7534-94-3		0.0222	mg
			Supplier	Silver (Ag)	7440-22-4		0.3016	mg
			Supplier	Isobornyl Acrylate	5888-33-5		0.0222	mg
			Supplier	Misc.	Proprietary Data		0.0019	mg
			Supplier	Tricyclo[5.2.1.02,6]decanedimethanol Diacrylate (C18H24O4)	42594-17-2		0.0222	mg
Lead Frame	33.6	mg	Supplier	Silver (Ag)	7440-22-4		0.336	mg
			Supplier	Tin (Sn)	7440-31-5		0.084	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0739	mg
			Supplier	Chromium (Cr)	7440-47-3		0.084	mg
			Supplier	Copper (Cu)	7440-50-8		33.0221	mg
Mold Compound-Black	37.0	mg		Epoxy resin	proprietary data		1.739	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.7	mg
			Supplier	Carbon Black (C)	1333-86-4		0.037	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		29.785	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.739	mg
Plating	1.3	mg	Supplier	Tin (Sn)	7440-31-5		1.3	mg
Wire Bond - Au	0.36	mg	Supplier	Gold (Au)	7440-57-5		0.36	mg